

The information below reflects a change that is being implemented.

Notice Date: 05/26/2005

Product Category: Linear Devices; CAN Communication; 24xxx; SDP

Notification Subject: Change #554 - QUALIFICATION OF 14L SOIC ETCHED LEADFRAME WITH 98X235 PADDLE AT MTAI

Notification Body:

Microchip Part Number(s)

HCS1370

HCS370

HCS462

HCS1370

HCS370

HCS462

MCP25020

MCP25025

MCP25050

MCP25055

24AA16

24C16B

24LC16B

MCP42010

Description of Change:

NEW LARGER PADDLE LEADFRAME QUAL

Effects on Data Sheet:

NONE

Reason for Change:

SECOND SOURCE

Estimated Change Implementation Date(s):

JUNE, 2005

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)

SHIP CONTAINER MARKING, COO

i2 Technologies US, Inc.

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